

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE BOARD OF PATENT APPEALS
AND INTERFERENCES

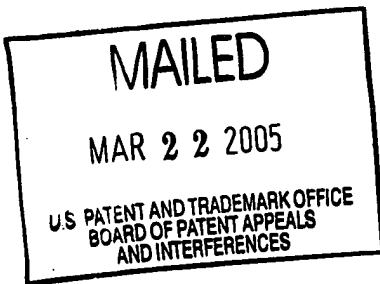
Ex parte GILROY J. VANDENTOP
and
JUN-FEI ZHENG

Application 10/020,911

ORDER RETURNING UNDOCKETED APPEAL TO EXAMINER

This application was electronically received at the Board of Patent Appeals and Interferences on March 7, 2005. A review of the application has revealed that the application is not ready for docketing as an appeal. Accordingly, the application is herewith electronically returned to the examiner. The matters requiring attention prior to docketing are identified below.

A copy of the Fan reference ("Copper Wafer Bonding," Electrochemical and Solid State Letters, 2(10) pp. 534-536 (1999)) relied on by the Examiner on page 3 of the Examiner's Answer mailed December 27, 2004, was not located in the Image File Wrapper (IFW).



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Accordingly, it is

ORDERED that the application is returned to the
examiner to:

1. have a complete copy of the Fan reference scanned
into the IFW file;
2. notify applicants of the action taken; and
2. for such further action as may be appropriate.

BOARD OF PATENT APPEALS
AND INTERFERENCES

By:

A handwritten signature in black ink, appearing to read 'D. M. Shaw', is written over a horizontal line.

DALE M. SHAW
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